

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	28	("3399254" "3745623" "4505746" "4604106" "4695321" "4861350" "4954139" "5505748" "5690706" "5728637" "5912217" "5954147" "6315871" "6342301").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 06:37
L2	7	I1 and (nano nanodiamond nanodiamonds (nano adj diamond) (nano adj diamonds))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:09
L3	21	("20030194961" "20040033771" "3605349" "5435816" "5958794" "6007407" "6228133" "6354929" "6612917" "6632129").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 06:46
L4	51712	(nano nanodiamond nanodiamonds (nano adj diamond) (nano adj diamonds)) (sub adj micron)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:11
L5	498262	polishing grinding abrading	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:09
L6	1117399	cutting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:09
L7	1530120	I5 I6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:09
L8	9497	I4 and I7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:10

L9	3005208	wafer wafers semiconductor semiconductors substrate substrates	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:10
L10	59725	cmp (chemical adj mechanical adj polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:10
L11	24022	I9 with I10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:19
L12	1435	I8 and I11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 07:11
L13	20060	nanodiamond nanodiamonds nanoparticle nanoparticles nanogrit nanogrits (sub adj micron adj (diamond diamonds particle particles grit grits)) (nano adj (diamond diamonds particle particles grit grits))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:15
L14	236	I13 with I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:18
L15	22	I11 and I14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:18
L16	4	I15 and (diamond diamonds)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:15

L17	430	I13 same I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:18
L18	8	I11 same I14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:18
L19	36072	I9 same I10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:19
L20	41	I17 and I19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:19
L21	9	I20 and (diamond diamonds)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:28
L22	618	I9 same I10 same (diamond diamonds)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:29
L23	2176	fixed adj abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:29
L24	3	I23 and (diamond diamonds) and I13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:46

L25	47	I23 same (organic with (binder binders))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 08:47
-----	----	--	---	----	-----	------------------